

4

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D

D

C

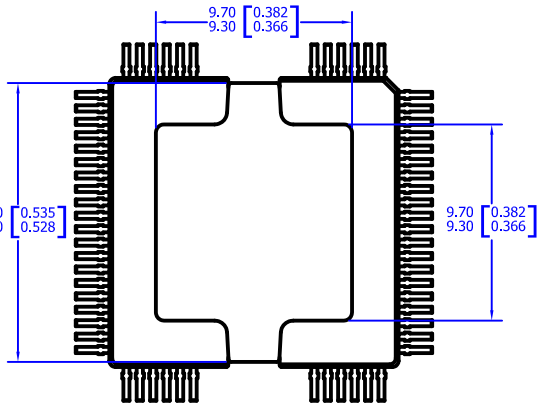
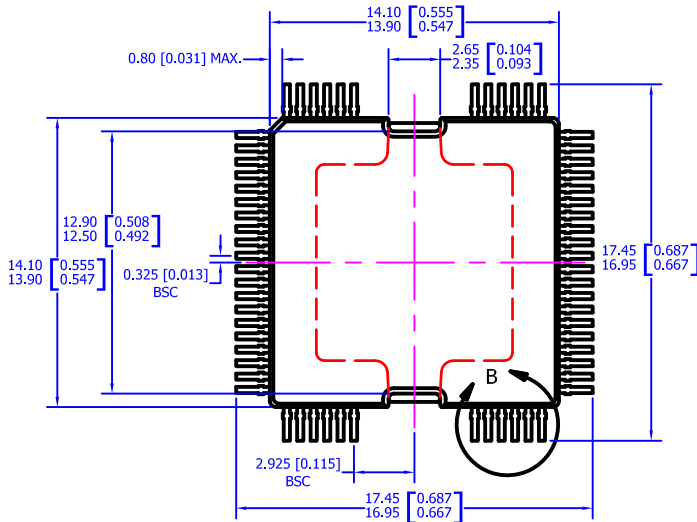
C

B

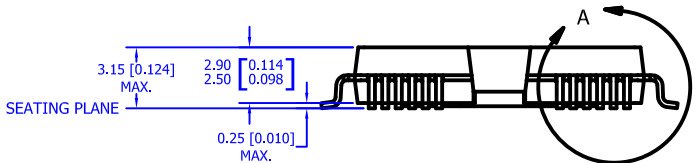
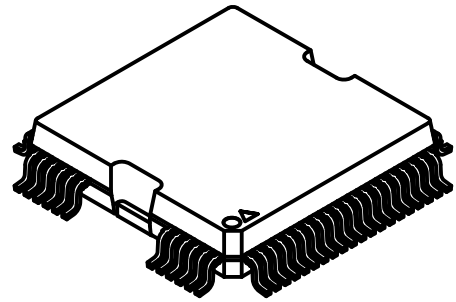
B

A

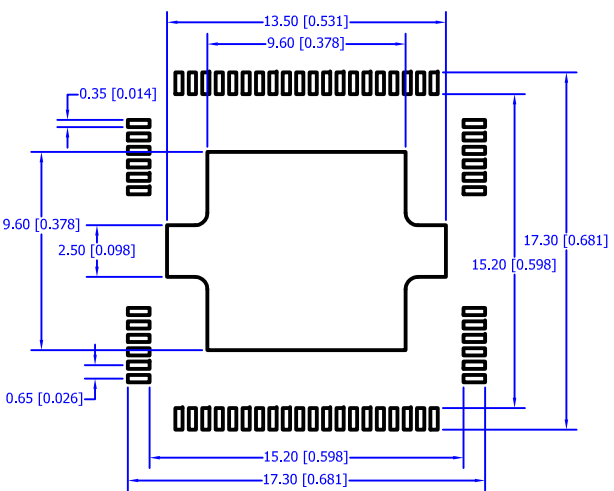
A



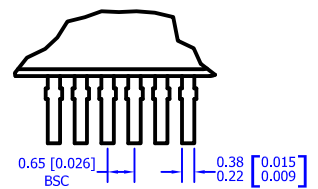
BOTTOM VIEW



DETAIL A



SURFACE MOUNT LAYOUT



DETAIL B

NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Chamfered corner denotes pin 1.
4. Heat slug: C10200 copper.
5. Lead frame: C19400 copper.
6. Mold compound: EME6600CSP epoxy.
7. Package weight (estimated): 0.71 oz. [2 g].
8. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED	
.XX	= ±.01
.XXX	= ±.005
ANG.	= ±.5°



TITLE:	64-PIN QFP (JEDEC MO-188)		MODEL:	HQ	
SUBJECT:	MECHANICAL PACKAGE OUTLINE		ENGINEER:	DAG	P.ECK
DRAWN BY:	P.ECK	DCA:	80024	SH:	1 OF 1
DATE:	02MAY08	REV:	A	FILENAME:	HQ

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